

Size $12.5 \times 12.5 \times 8.5$ (mm)

Series/Type: B82477P4

Date: October 2008



B82477P4

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SMD

Rated inductance 0.82 μH to 1000 μH Rated current 0.6 A to 11 A

Construction

- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding soldered to terminals
- Injection molded base

Features

- High mechanical stability
- High rated current, low DC resistance
- Temperature range up to 150 °C
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020C
- Qualified to AEC-Q200
- RoHS-compatible

Applications

- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics

Terminals

- Base material Cu (L \leq 10 μ H), CuSn6P (L \geq 15 μ H)
- Layer composition Ni, Sn (lead-free)
- Electro-plated

Marking

- Marking on component:
 Manufacturer, L value (μH, coded),
 manufacturing date (YWWD)
- Minimum data on reel: Manufacturer, ordering code, L value, quantity, date of packing

Delivery mode and packing unit

- lacksquare 24-mm blister tape, wound on 330-mm \varnothing reel
- Packing unit: 350 pcs./reel



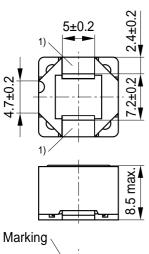


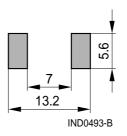
B82477P4

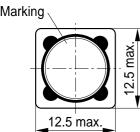
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Dimensional drawing and layout recommendation





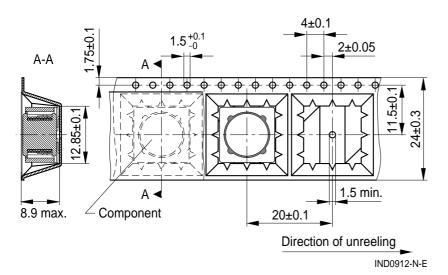


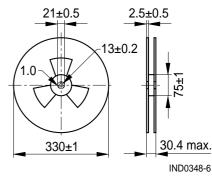
1) Soldering area IND0572-K-E

Dimensions in mm

Taping and packing

Blister tape





Reel

Dimensions in mm



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Technical data and measuring conditions

| Rated inductance L _R | Measured with LCR meter Agilent 4284A at frequency f _L 0.1 V, 20 °C | | | |
|-------------------------------------|--|--|--|--|
| Rated temperature T _R | 85 °C | | | |
| Rated current I _R | Max. permissible DC with temperature increase of \leq 40 K at rated temperature | | | |
| Saturation current I _{sat} | Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10% | | | |
| DC resistance R _{max} | Measured at 20 °C | | | |
| Solderability (lead-free) | Dip and look method Sn95.5Ag3.8Cu0.7: (245 ± 5) °C, (5 ± 0.3) s Wetting of soldering area \geq 90% (based on IEC 60068-2-58) | | | |
| Resistance to soldering heat | 260 °C, 40 s (as referenced in JEDEC J-STD 020C) | | | |
| Climatic category | 55/150/56 (to IEC 60068-1) | | | |
| Storage conditions | Mounted: -55 °C +150 °C Packaged: -25 °C +40 °C, ≤ 75% RH | | | |
| Weight | Approx. 4 g | | | |



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Characteristics and ordering codes

| L_R | Tolerance | f_{L} | I _R | I _{sat} | R _{max} | Ordering code |
|-------|-----------|---------|----------------|------------------|------------------|-----------------|
| μΗ | | MHz | А | Α | Ω | |
| 0.82 | ±20% ≙ M | 0.1 | 11.00 | 15.00 | 0.0055 | B82477P4821M000 |
| 2.0 | | 0.1 | 8.90 | 11.00 | 0.0080 | B82477P4202M000 |
| 3.3 | | 0.1 | 8.10 | 9.60 | 0.0100 | B82477P4332M000 |
| 3.9 | | 0.1 | 8.00 | 9.50 | 0.0100 | B82477P4392M000 |
| 4.7 | | 0.1 | 7.30 | 8.40 | 0.0120 | B82477P4472M000 |
| 5.6 | | 0.1 | 7.15 | 8.30 | 0.0125 | B82477P4562M000 |
| 6.8 | | 0.1 | 6.60 | 7.30 | 0.0150 | B82477P4682M000 |
| 10 | | 0.1 | 5.80 | 6.40 | 0.0190 | B82477P4103M000 |
| 15 | | 0.1 | 4.80 | 5.20 | 0.0285 | B82477P4153M000 |
| 22 | | 0.1 | 4.15 | 4.35 | 0.035 | B82477P4223M000 |
| 33 | | 0.1 | 3.35 | 3.50 | 0.052 | B82477P4333M000 |
| 47 | | 0.1 | 2.80 | 3.00 | 0.067 | B82477P4473M000 |
| 68 | | 0.1 | 2.35 | 2.45 | 0.098 | B82477P4683M000 |
| 82 | | 0.1 | 2.10 | 2.25 | 0.120 | B82477P4823M000 |
| 100 | | 0.1 | 1.87 | 1.95 | 0.138 | B82477P4104M000 |
| 150 | | 0.1 | 1.61 | 1.70 | 0.185 | B82477P4154M000 |
| 220 | | 0.1 | 1.24 | 1.35 | 0.305 | B82477P4224M000 |
| 330 | | 0.1 | 1.02 | 1.15 | 0.460 | B82477P4334M000 |
| 470 | | 0.1 | 0.86 | 0.95 | 0.640 | B82477P4474M000 |
| 680 | | 0.1 | 0.69 | 0.78 | 1.05 | B82477P4684M000 |
| 1000 | | 0.1 | 0.60 | 0.65 | 1.38 | B82477P4105M000 |

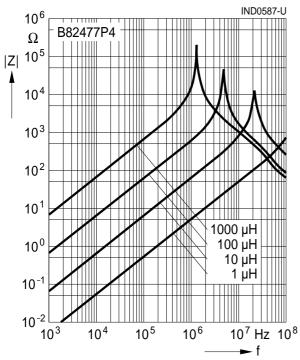
Version with height 4.8 mm on request (same footprint). Type: B82477P1 Version with height 6.5 mm on request (same footprint). Type: B82477P2.





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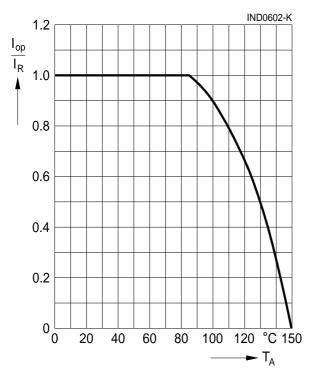
Impedance |Z| versus frequency f measured with impedance analyzer Agilent 4294A, typical values at 20 °C



Current derating I_{op}/I_R

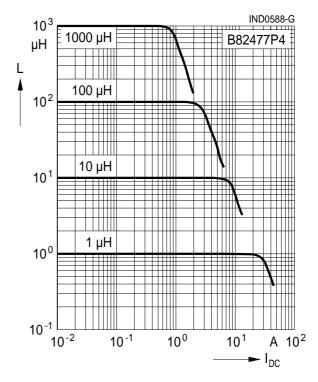
versus ambient temperature TA

(rated temperature $T_R = 85$ °C)



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Inductance L versus DC load current I_{DC} measured with LCR meter Agilent 4275A, typical values at 20 °C





Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.



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